PRODUCTS



R500 Solder Paste

Kester R500 is a water-soluble solder paste formula specifically designed as a consistent dot dispensing paste for automated dispense equipment. This solder paste exhibits excellent wetting characteristics in a wide range of profiles. The activator package in this formula is extremely aggressive. It is active enough to remove tenacious oxide layers or to solder to OSP coated boards. R500 is a water-soluble formula that maintains its activity and tackiness characteristics for up to 8 hours.

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Product Offerings | Data Sheets and SDS

Alloy	Powder Size	Type	Halogen Content	Lead Content	Description	Part #	Process
Sn63Pb37	3	Water-Soluble	Contains Halogen	Leaded	R500 Sn63Pb37 T3 86% 35g SYR	7017080520	Dispense
Sn96.5Ag3.0Cu0.5	3	Water-Soluble	Contains Halogen	Lead-Free	Sn96.5Ag3.0Cu0.5 T3 85.5% 35g SY	7017090820	Dispense
Sn63Pb37	3	Water-Soluble	Contains Halogen	Leaded	R500 Sn63Pb37 T3 86% 100g SYR	7017080504	Dispense

Process Compatible Products

2331-ZX Soldering Flux



331 Flux-Cored Wire



HM531 Solder Paste



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